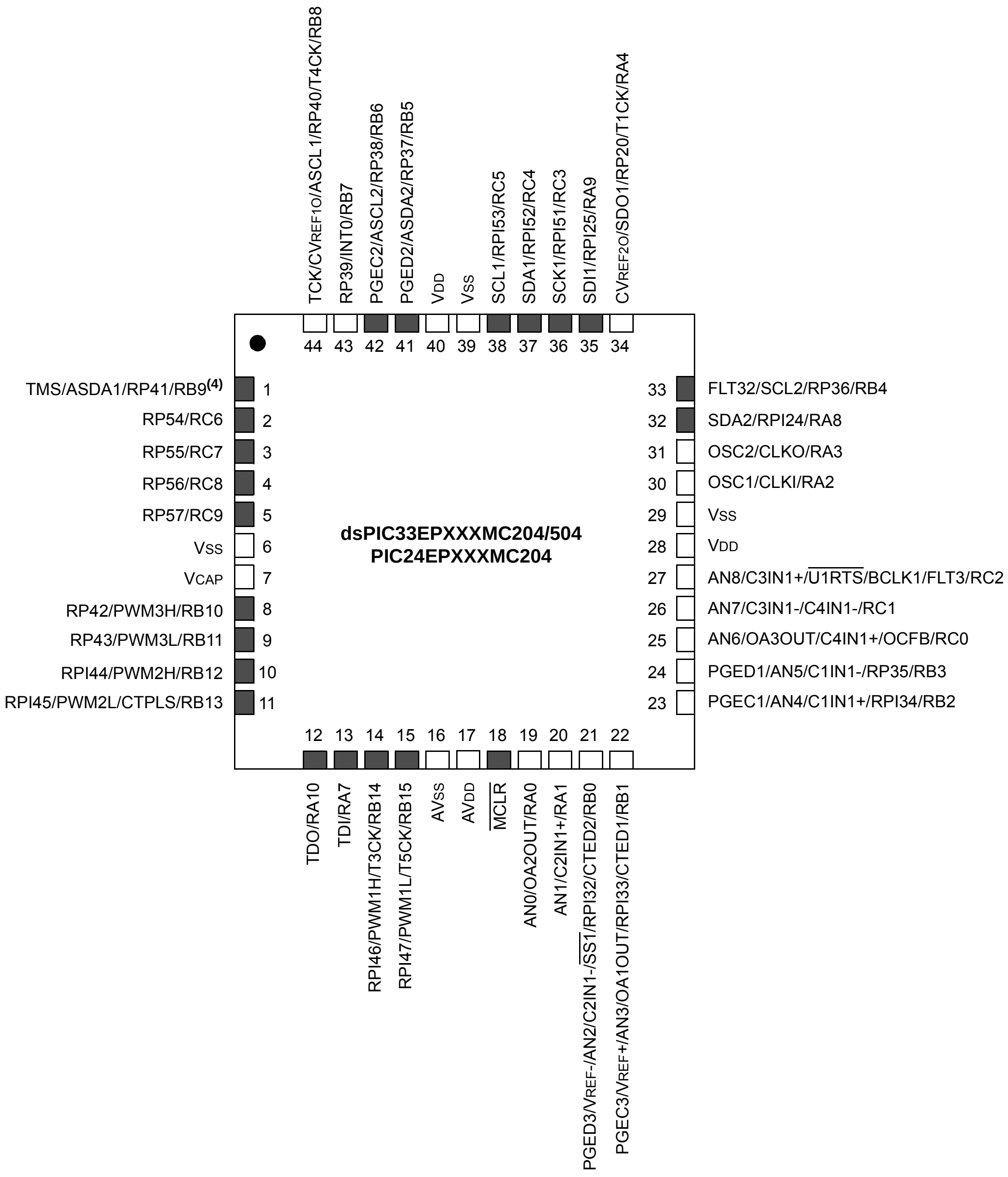
Details	
Product Status	Obsolete
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	21
Program Memory Size	32KB (10.7K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep32mc202t-e-ss

Pin Diagrams (Continued)

44-Pin QFN(1,2,3)

▪ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 “Peripheral Pin Select (PPS)”** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 “I/O Ports”** for more information.

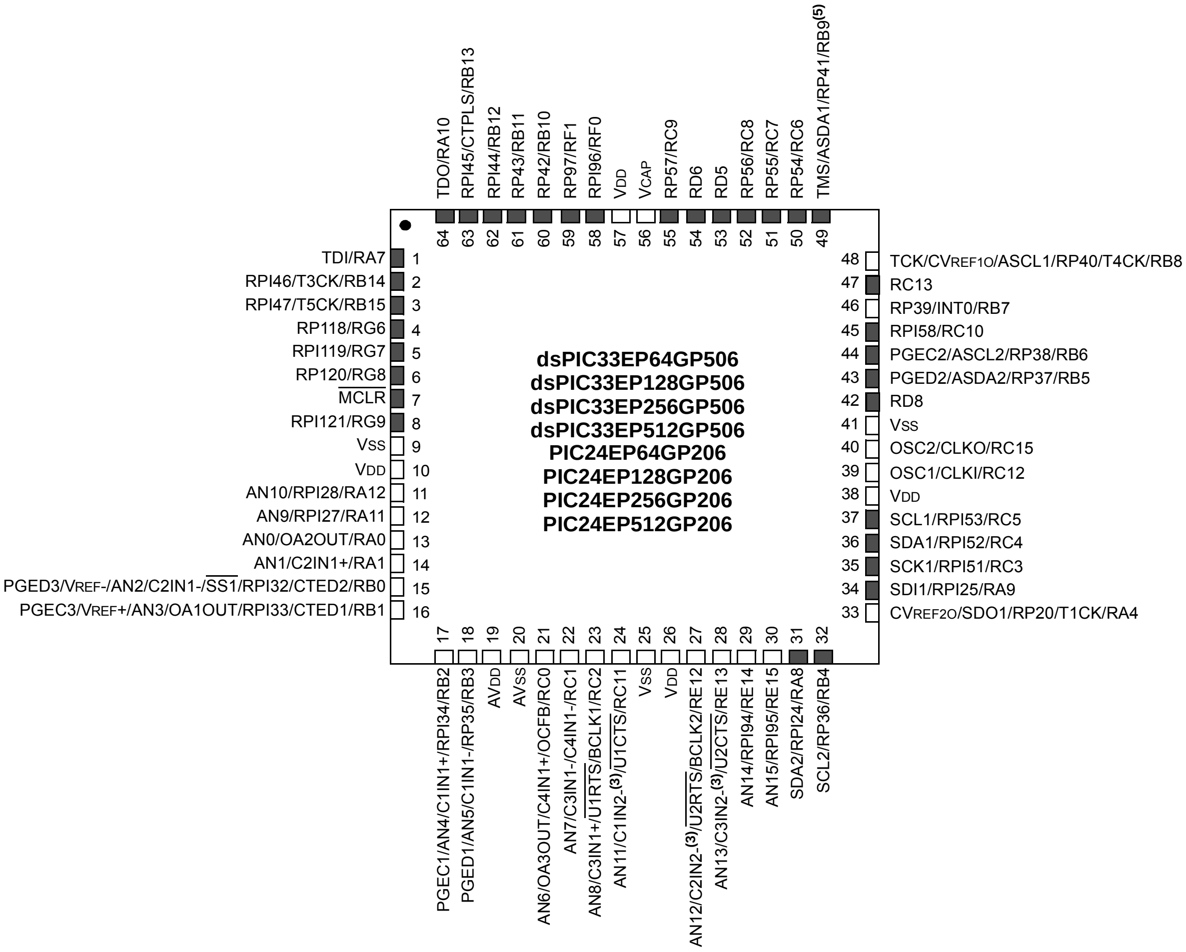
3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

Pin Diagrams (Continued)

64-Pin QFN[1,2,3,4]

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: This pin is not available as an input when OPMODE (CMxCON<10>) = 1.

4: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

5: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

4.5 Instruction Addressing Modes

The addressing modes shown in Table 4-63 form the basis of the addressing modes optimized to support the specific features of individual instructions. The addressing modes provided in the `MAC` class of instructions differ from those in the other instruction types.

4.5.1 FILE REGISTER INSTRUCTIONS

Most file register instructions use a 13-bit address field (f) to directly address data present in the first 8192 bytes of data memory (Near Data Space). Most file register instructions employ a working register, W0, which is denoted as WREG in these instructions. The destination is typically either the same file register or WREG (with the exception of the `MUL` instruction), which writes the result to a register or register pair. The `MOV` instruction allows additional flexibility and can access the entire Data Space.

4.5.2 MCU INSTRUCTIONS

The three-operand MCU instructions are of the form:

`Operand 3 = Operand 1 <function> Operand 2`

where Operand 1 is always a working register (that is, the addressing mode can only be Register Direct), which is referred to as Wb. Operand 2 can be a W register fetched from data memory or a 5-bit literal. The result location can either be a W register or a data memory location. The following addressing modes are supported by MCU instructions:

- Register Direct
- Register Indirect
- Register Indirect Post-Modified
- Register Indirect Pre-Modified
- 5-Bit or 10-Bit Literal

Note: Not all instructions support all the addressing modes given above. Individual instructions can support different subsets of these addressing modes.

TABLE 4-63: FUNDAMENTAL ADDRESSING MODES SUPPORTED

Addressing Mode	Description
File Register Direct	The address of the file register is specified explicitly.
Register Direct	The contents of a register are accessed directly.
Register Indirect	The contents of Wn form the Effective Address (EA).
Register Indirect Post-Modified	The contents of Wn form the EA. Wn is post-modified (incremented or decremented) by a constant value.
Register Indirect Pre-Modified	Wn is pre-modified (incremented or decremented) by a signed constant value to form the EA.
Register Indirect with Register Offset (Register Indexed)	The sum of Wn and Wb forms the EA.
Register Indirect with Literal Offset	The sum of Wn and a literal forms the EA.

5.0 FLASH PROGRAM MEMORY

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Flash Programming"** (DS70609) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices contain internal Flash program memory for storing and executing application code. The memory is readable, writable and erasable during normal operation over the entire VDD range.

Flash memory can be programmed in two ways:

- In-Circuit Serial Programming™ (ICSP™) programming capability
- Run-Time Self-Programming (RTSP)

ICSP allows for a dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X device to be serially programmed while in the end application circuit. This is done with two lines for programming clock and programming data (one of the alternate programming pin pairs: PGECx/PGEDx), and three other lines for power (VDD), ground (VSS) and Master Clear ($\overline{\text{MCLR}}$). This allows customers to manufacture boards with unprogrammed devices and then program the device just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

RTSP is accomplished using `TBLRD` (Table Read) and `TBLWT` (Table Write) instructions. With RTSP, the user application can write program memory data a single program memory word, and erase program memory in blocks or 'pages' of 1024 instructions (3072 bytes) at a time.

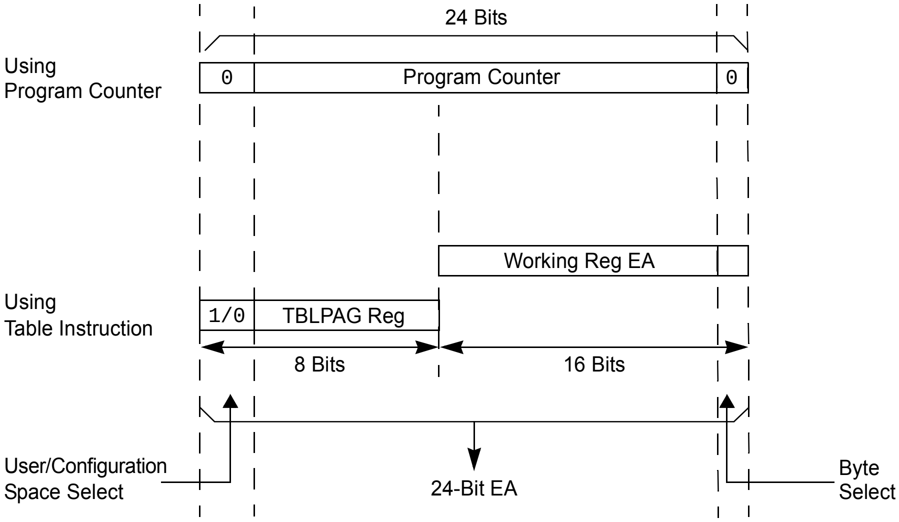
5.1 Table Instructions and Flash Programming

Regardless of the method used, all programming of Flash memory is done with the Table Read and Table Write instructions. These allow direct read and write access to the program memory space from the data memory while the device is in normal operating mode. The 24-bit target address in the program memory is formed using bits<7:0> of the TBLPAG register and the Effective Address (EA) from a W register, specified in the table instruction, as shown in Figure 5-1.

The `TBLRDL` and the `TBLWTL` instructions are used to read or write to bits<15:0> of program memory. `TBLRDL` and `TBLWTL` can access program memory in both Word and Byte modes.

The `TBLRDH` and `TBLWTH` instructions are used to read or write to bits<23:16> of program memory. `TBLRDH` and `TBLWTH` can also access program memory in Word or Byte mode.

FIGURE 5-1: ADDRESSING FOR TABLE REGISTERS



10.0 POWER-SAVING FEATURES

> **Note 1:** This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Watchdog Timer and Power-Saving Modes"** (DS70615) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).
>
> **2:** Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices provide the ability to manage power consumption by selectively managing clocking to the CPU and the peripherals. In general, a lower clock frequency and a reduction in the number of peripherals being clocked constitutes lower consumed power.

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices can manage power consumption in four ways:

- Clock Frequency
- Instruction-Based Sleep and Idle modes
- Software-Controlled Doze mode
- Selective Peripheral Control in Software

Combinations of these methods can be used to selectively tailor an application's power consumption while still maintaining critical application features, such as timing-sensitive communications.

10.1 Clock Frequency and Clock Switching

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices allow a wide range of clock frequencies to be selected under application control. If the system clock configuration is not locked, users can choose low-power or high-precision oscillators by simply changing the NOSCx bits (OSCCON<10:8>). The process of changing a system clock during operation, as well as limitations to the process, are discussed in more detail in **Section 9.0 "Oscillator Configuration"**.

10.2 Instruction-Based Power-Saving Modes

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices have two special power-saving modes that are entered through the execution of a special `PWRSAV` instruction. Sleep mode stops clock operation and halts all code execution. Idle mode halts the CPU and code execution, but allows peripheral modules to continue operation. The assembler syntax of the `PWRSAV` instruction is shown in Example 10-1.

> **Note:** `SLEEP_MODE` and `IDLE_MODE` are constants defined in the assembler include file for the selected device.

Sleep and Idle modes can be exited as a result of an enabled interrupt, WDT time-out or a device Reset. When the device exits these modes, it is said to "wake-up".

EXAMPLE 10-1: `PWRSAV` INSTRUCTION SYNTAX

```
PWRSAV  #SLEEP_MODE    ; Put the device into Sleep mode
PWRSAV  #IDLE_MODE     ; Put the device into Idle mode
```

REGISTER 10-1: PMD1: PERIPHERAL MODULE DISABLE CONTROL REGISTER 1

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0
T5MD	T4MD	T3MD	T2MD	T1MD	QEI1MD(1)	PWMMD(1)	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0
I2C1MD	U2MD	U1MD	SPI2MD	SPI1MD	—	C1MD(2)	AD1MD
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15	**T5MD:** Timer5 Module Disable bit 1 = Timer5 module is disabled 0 = Timer5 module is enabled
bit 14	**T4MD:** Timer4 Module Disable bit 1 = Timer4 module is disabled 0 = Timer4 module is enabled
bit 13	**T3MD:** Timer3 Module Disable bit 1 = Timer3 module is disabled 0 = Timer3 module is enabled
bit 12	**T2MD:** Timer2 Module Disable bit 1 = Timer2 module is disabled 0 = Timer2 module is enabled
bit 11	**T1MD:** Timer1 Module Disable bit 1 = Timer1 module is disabled 0 = Timer1 module is enabled
bit 10	**QEI1MD:** QEI1 Module Disable bit(1) 1 = QEI1 module is disabled 0 = QEI1 module is enabled
bit 9	**PWMMD:** PWM Module Disable bit(1) 1 = PWM module is disabled 0 = PWM module is enabled
bit 8	**Unimplemented:** Read as ‘0’
bit 7	**I2C1MD:** I2C1 Module Disable bit 1 = I2C1 module is disabled 0 = I2C1 module is enabled
bit 6	**U2MD:** UART2 Module Disable bit 1 = UART2 module is disabled 0 = UART2 module is enabled
bit 5	**U1MD:** UART1 Module Disable bit 1 = UART1 module is disabled 0 = UART1 module is enabled
bit 4	**SPI2MD:** SPI2 Module Disable bit 1 = SPI2 module is disabled 0 = SPI2 module is enabled

Note 1: This bit is available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

2: This bit is available on dsPIC33EPXXXGP50X and dsPIC33EPXXXMC50X devices only.

15.1 Output Compare Resources

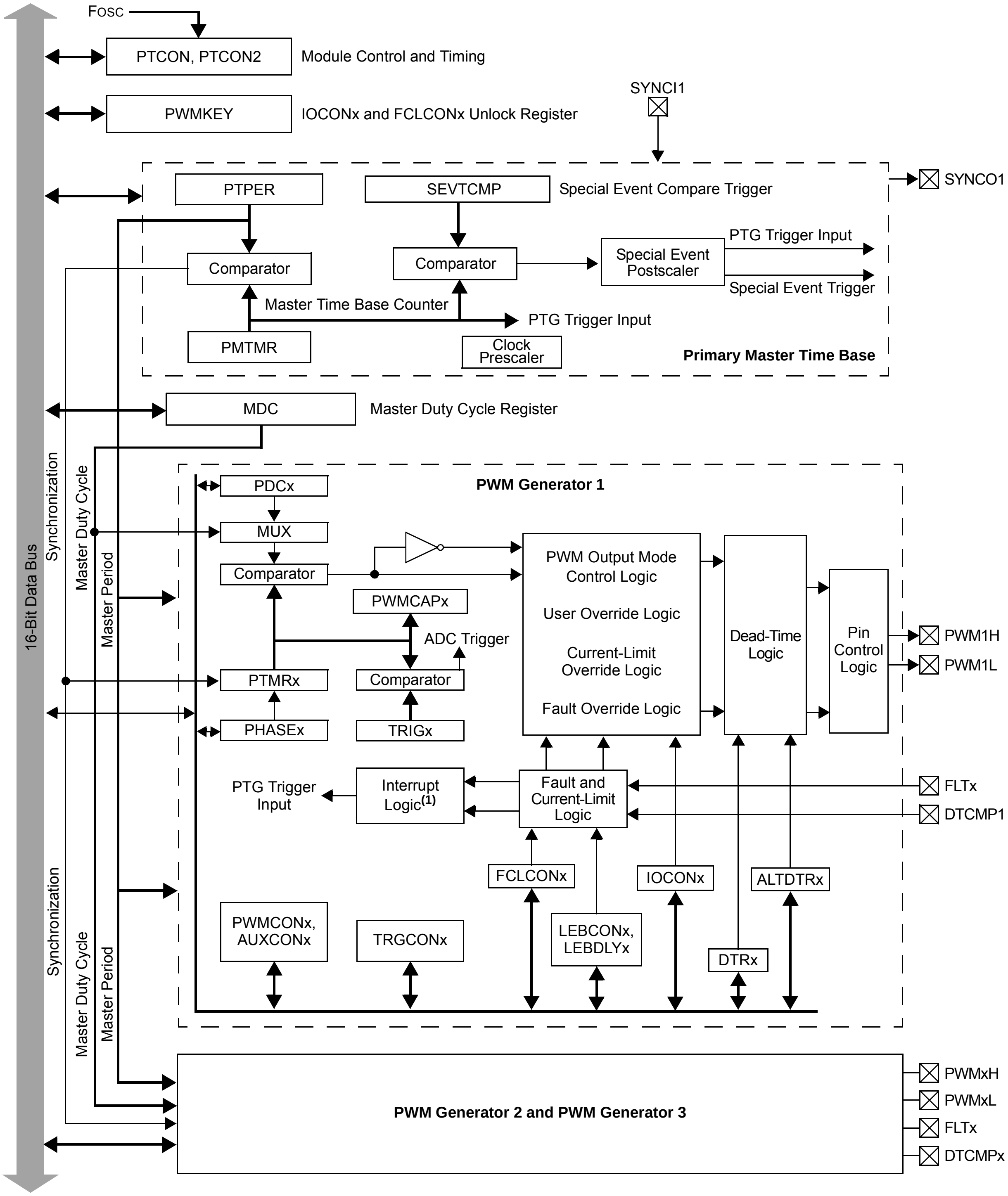
Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/ Devices.aspx?dDocName=en555464

15.1.1 KEY RESOURCES

- **"Output Compare"** (DS70358) in the *"dsPIC33/ PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

FIGURE 16-2: HIGH-SPEED PWMx MODULE REGISTER INTERCONNECTION DIAGRAM



Note 1: The PWM interrupts are generated by logically ORing the FLTSTAT, CLSTAT and TRGSTAT status bits for the given PWM generator. Refer to the "*dsPIC33/PIC24 Family Reference Manual*", **"High-Speed PWM"** (DS70645) for more information.

REGISTER 16-16: LEBCONx: PWMx LEADING-EDGE BLANKING CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
PHR	PHF	PLR	PLF	FLTLEBEN	CLLEBEN	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	BCH[1]	BCL[1]	BPHH	BPHL	BPLH	BPLL
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **PHR:** PWMxH Rising Edge Trigger Enable bit
`1` = Rising edge of PWMxH will trigger Leading-Edge Blanking counter
`0` = Leading-Edge Blanking ignores rising edge of PWMxH

bit 14 **PHF:** PWMxH Falling Edge Trigger Enable bit
`1` = Falling edge of PWMxH will trigger Leading-Edge Blanking counter
`0` = Leading-Edge Blanking ignores falling edge of PWMxH

bit 13 **PLR:** PWMxL Rising Edge Trigger Enable bit
`1` = Rising edge of PWMxL will trigger Leading-Edge Blanking counter
`0` = Leading-Edge Blanking ignores rising edge of PWMxL

bit 12 **PLF:** PWMxL Falling Edge Trigger Enable bit
`1` = Falling edge of PWMxL will trigger Leading-Edge Blanking counter
`0` = Leading-Edge Blanking ignores falling edge of PWMxL

bit 11 **FLTLEBEN:** Fault Input Leading-Edge Blanking Enable bit
`1` = Leading-Edge Blanking is applied to selected Fault input
`0` = Leading-Edge Blanking is not applied to selected Fault input

bit 10 **CLLEBEN:** Current-Limit Leading-Edge Blanking Enable bit
`1` = Leading-Edge Blanking is applied to selected current-limit input
`0` = Leading-Edge Blanking is not applied to selected current-limit input

bit 9-6 **Unimplemented:** Read as ‘`0`’

bit 5 **BCH:** Blanking in Selected Blanking Signal High Enable bit[1]
`1` = State blanking (of current-limit and/or Fault input signals) when selected blanking signal is high
`0` = No blanking when selected blanking signal is high

bit 4 **BCL:** Blanking in Selected Blanking Signal Low Enable bit[1]
`1` = State blanking (of current-limit and/or Fault input signals) when selected blanking signal is low
`0` = No blanking when selected blanking signal is low

bit 3 **BPHH:** Blanking in PWMxH High Enable bit
`1` = State blanking (of current-limit and/or Fault input signals) when PWMxH output is high
`0` = No blanking when PWMxH output is high

bit 2 **BPHL:** Blanking in PWMxH Low Enable bit
`1` = State blanking (of current-limit and/or Fault input signals) when PWMxH output is low
`0` = No blanking when PWMxH output is low

bit 1 **BPLH:** Blanking in PWMxL High Enable bit
`1` = State blanking (of current-limit and/or Fault input signals) when PWMxL output is high
`0` = No blanking when PWMxL output is high

bit 0 **BPLL:** Blanking in PWMxL Low Enable bit
`1` = State blanking (of current-limit and/or Fault input signals) when PWMxL output is low
`0` = No blanking when PWMxL output is low

Note 1: The blanking signal is selected via the BLANKSELx bits in the AUXCONx register.

REGISTER 21-8: CxEC: ECANx TRANSMIT/RECEIVE ERROR COUNT REGISTER

R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
TERRCNT<7:0>							
bit 15							bit 8

R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
RERRCNT<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8	**TERRCNT<7:0>:** Transmit Error Count bits
bit 7-0	**RERRCNT<7:0>:** Receive Error Count bits

REGISTER 21-9: CxCFG1: ECANx BAUD RATE CONFIGURATION REGISTER 1

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SJW1	SJW0	BRP5	BRP4	BRP3	BRP2	BRP1	BRP0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as ‘0’

bit 7-6 **SJW<1:0>:** Synchronization Jump Width bits

11 = Length is 4 x T_Q
10 = Length is 3 x T_Q
01 = Length is 2 x T_Q
00 = Length is 1 x T_Q

bit 5-0 **BRP<5:0>:** Baud Rate Prescaler bits

11 1111 = T_Q = 2 x 64 x 1/F_{CAN}
•
•
•
00 0010 = T_Q = 2 x 3 x 1/F_{CAN}
00 0001 = T_Q = 2 x 2 x 1/F_{CAN}
00 0000 = T_Q = 2 x 1 x 1/F_{CAN}

NOTES:

TABLE 24-2: PTG OUTPUT DESCRIPTIONS

PTG Output Number	PTG Output Description
PTGO0	Trigger/Synchronization Source for OC1
PTGO1	Trigger/Synchronization Source for OC2
PTGO2	Trigger/Synchronization Source for OC3
PTGO3	Trigger/Synchronization Source for OC4
PTGO4	Clock Source for OC1
PTGO5	Clock Source for OC2
PTGO6	Clock Source for OC3
PTGO7	Clock Source for OC4
PTGO8	Trigger/Synchronization Source for IC1
PTGO9	Trigger/Synchronization Source for IC2
PTGO10	Trigger/Synchronization Source for IC3
PTGO11	Trigger/Synchronization Source for IC4
PTGO12	Sample Trigger for ADC
PTGO13	Sample Trigger for ADC
PTGO14	Sample Trigger for ADC
PTGO15	Sample Trigger for ADC
PTGO16	PWM Time Base Synchronous Source for PWM(1)
PTGO17	PWM Time Base Synchronous Source for PWM(1)
PTGO18	Mask Input Select for Op Amp/Comparator
PTGO19	Mask Input Select for Op Amp/Comparator
PTGO20	Reserved
PTGO21	Reserved
PTGO22	Reserved
PTGO23	Reserved
PTGO24	Reserved
PTGO25	Reserved
PTGO26	Reserved
PTGO27	Reserved
PTGO28	Reserved
PTGO29	Reserved
PTGO30	PTG Output to PPS Input Selection
PTGO31	PTG Output to PPS Input Selection

Note 1: This feature is only available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices.

REGISTER 25-2: CMxCON: COMPARATOR x CONTROL REGISTER (x = 1, 2 OR 3)

R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0
CON	COE[(2)]	CPOL	—	—	OPMODE	CEVT	COUT
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0
EVPOL1	EVPOL0	—	CREF[(1)]	—	—	CCH1[(1)]	CCH0[(1)]
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **CON:** Op Amp/Comparator Enable bit

1 = Op amp/comparator is enabled
0 = Op amp/comparator is disabled

bit 14 **COE:** Comparator Output Enable bit[(2)]

1 = Comparator output is present on the CxOUT pin
0 = Comparator output is internal only

bit 13 **CPOL:** Comparator Output Polarity Select bit

1 = Comparator output is inverted
0 = Comparator output is not inverted

bit 12-11 **Unimplemented:** Read as ‘0’

bit 10 **OPMODE:** Op Amp/Comparator Operation Mode Select bit

1 = Circuit operates as an op amp
0 = Circuit operates as a comparator

bit 9 **CEVT:** Comparator Event bit

1 = Comparator event according to the EVPOL<1:0> settings occurred; disables future triggers and interrupts until the bit is cleared
0 = Comparator event did not occur

bit 8 **COUT:** Comparator Output bit

When CPOL = 0 (non-inverted polarity):
1 = VIN+ > VIN-
0 = VIN+ < VIN-

When CPOL = 1 (inverted polarity):
1 = VIN+ < VIN-
0 = VIN+ > VIN-

Note 1: Inputs that are selected and not available will be tied to VSS. See the **“Pin Diagrams”** section for available inputs for each package.

2: This output is not available when OPMODE (CMxCON<10>) = 1.

REGISTER 25-7: CVRCON: COMPARATOR VOLTAGE REFERENCE CONTROL REGISTER

U-0	R/W-0	U-0	U-0	U-0	R/W-0	U-0	U-0
—	CVR2OE(1)	—	—	—	VREFSEL	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CVREN	CVR1OE(1)	CVRR	CVRSS(2)	CVR3	CVR2	CVR1	CVR0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15	**Unimplemented:** Read as ‘`0`’
bit 14	**CVR2OE:** Comparator Voltage Reference 2 Output Enable bit(1) `1` = (AVDD – AVSS)/2 is connected to the CVREF2O pin `0` = (AVDD – AVSS)/2 is disconnected from the CVREF2O pin
bit 13-11	**Unimplemented:** Read as ‘`0`’
bit 10	**VREFSEL:** Comparator Voltage Reference Select bit `1` = CVREFIN = VREF+ `0` = CVREFIN is generated by the resistor network
bit 9-8	**Unimplemented:** Read as ‘`0`’
bit 7	**CVREN:** Comparator Voltage Reference Enable bit `1` = Comparator voltage reference circuit is powered on `0` = Comparator voltage reference circuit is powered down
bit 6	**CVR1OE:** Comparator Voltage Reference 1 Output Enable bit(1) `1` = Voltage level is output on the CVREF1O pin `0` = Voltage level is disconnected from then CVREF1O pin
bit 5	**CVRR:** Comparator Voltage Reference Range Selection bit `1` = CVRSRC/24 step-size `0` = CVRSRC/32 step-size
bit 4	**CVRSS:** Comparator Voltage Reference Source Selection bit(2) `1` = Comparator voltage reference source, CVRSRC = (VREF+) – (AVSS) `0` = Comparator voltage reference source, CVRSRC = AVDD – AVSS
bit 3-0	**CVR<3:0>** Comparator Voltage Reference Value Selection 0 ≤ CVR<3:0> ≤ 15 bits When CVRR = `1`: CVREFIN = (CVR<3:0>/24) • (CVRSRC) When CVRR = `0`: CVREFIN = (CVRSRC/4) + (CVR<3:0>/32) • (CVRSRC)

Note 1: CVRxOE overrides the TRISx and the ANSELx bit settings.

2: In order to operate with CVRSS = `1`, at least one of the comparator modules must be enabled.

Most instructions are a single word. Certain double-word instructions are designed to provide all the required information in these 48 bits. In the second word, the 8 MSbs are '`0`'s. If this second word is executed as an instruction (by itself), it executes as a `NOP`.

The double-word instructions execute in two instruction cycles.

Most single-word instructions are executed in a single instruction cycle, unless a conditional test is true, or the Program Counter is changed as a result of the instruction, or a PSV or Table Read is performed, or an SFR register is read. In these cases, the execution takes multiple instruction cycles with the additional instruction cycle(s) executed as a `NOP`. Certain instructions that involve skipping over the subsequent instruction require either two or three cycles if the skip is performed, depending on whether the instruction being skipped is a single-word or two-word instruction. Moreover, double-word moves require two cycles.

> **Note:** For more details on the instruction set, refer to the *"16-bit MCU and DSC Programmer's Reference Manual"* (DS70157).
>
> For more information on instructions that take more than one instruction cycle to execute, refer to **"CPU"** (DS70359) in the *"dsPIC33/PIC24 Family Reference Manual"*, particularly the **"Instruction Flow Types"** section.

TABLE 28-1: SYMBOLS USED IN OPCODE DESCRIPTIONS

Field	Description
#text	Means literal defined by "`text`"
(text)	Means "content of `text`"
[text]	Means "the location addressed by `text`"
{ }	Optional field or operation
a ∈ {b, c, d}	a is selected from the set of values b, c, d
<n:m>	Register bit field
.b	Byte mode selection
.d	Double-Word mode selection
.S	Shadow register select
.w	Word mode selection (default)
Acc	One of two accumulators {A, B}
AWB	Accumulator write back destination address register ∈ {W13, [W13]+ = 2}
bit4	4-bit bit selection field (used in word addressed instructions) ∈ {0...15}
C, DC, N, OV, Z	MCU Status bits: Carry, Digit Carry, Negative, Overflow, Sticky Zero
Expr	Absolute address, label or expression (resolved by the linker)
f	File register address ∈ {0x0000...0x1FFF}
lit1	1-bit unsigned literal ∈ {0,1}
lit4	4-bit unsigned literal ∈ {0...15}
lit5	5-bit unsigned literal ∈ {0...31}
lit8	8-bit unsigned literal ∈ {0...255}
lit10	10-bit unsigned literal ∈ {0...255} for Byte mode, {0:1023} for Word mode
lit14	14-bit unsigned literal ∈ {0...16384}
lit16	16-bit unsigned literal ∈ {0...65535}
lit23	23-bit unsigned literal ∈ {0...8388608}; LSb must be '`0`'
None	Field does not require an entry, can be blank
OA, OB, SA, SB	DSP Status bits: ACCA Overflow, ACCB Overflow, ACCA Saturate, ACCB Saturate
PC	Program Counter
Slit10	10-bit signed literal ∈ {-512...511}
Slit16	16-bit signed literal ∈ {-32768...32767}
Slit6	6-bit signed literal ∈ {-16...16}
Wb	Base W register ∈ {W0...W15}
Wd	Destination W register ∈ { Wd, [Wd], [Wd++], [Wd--], [++Wd], [--Wd] }
Wdo	Destination W register ∈ { Wnd, [Wnd], [Wnd++], [Wnd--], [++Wnd], [--Wnd], [Wnd+Wb] }

TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax		Description	# of Words	# of Cycles[2]	Status Flags Affected
46	`MOV`	`MOV`	`f,Wn`	Move f to Wn	1	1	None
		`MOV`	`f`	Move f to f	1	1	None
		`MOV`	`f,WREG`	Move f to WREG	1	1	None
		`MOV`	`#lit16,Wn`	Move 16-bit literal to Wn	1	1	None
		`MOV.b`	`#lit8,Wn`	Move 8-bit literal to Wn	1	1	None
		`MOV`	`Wn,f`	Move Wn to f	1	1	None
		`MOV`	`Wso,Wdo`	Move Ws to Wd	1	1	None
		`MOV`	`WREG,f`	Move WREG to f	1	1	None
		`MOV.D`	`Wns,Wd`	Move Double from W(ns):W(ns + 1) to Wd	1	2	None
		`MOV.D`	`Ws,Wnd`	Move Double from Ws to W(nd + 1):W(nd)	1	2	None
47	`MOVPAG`	`MOVPAG`	`#lit10,DSRPAG`	Move 10-bit literal to DSRPAG	1	1	None
		`MOVPAG`	`#lit9,DSWPAG`	Move 9-bit literal to DSWPAG	1	1	None
		`MOVPAG`	`#lit8,TBLPAG`	Move 8-bit literal to TBLPAG	1	1	None
		`MOVPAG`	`Ws, DSRPAG`	Move Ws<9:0> to DSRPAG	1	1	None
		`MOVPAG`	`Ws, DSWPAG`	Move Ws<8:0> to DSWPAG	1	1	None
		`MOVPAG`	`Ws, TBLPAG`	Move Ws<7:0> to TBLPAG	1	1	None
48	`MOVSAC`	`MOVSAC`	`Acc,Wx,Wxd,Wy,Wyd,AWB`[1]	Prefetch and store accumulator	1	1	None
49	`MPY`	`MPY`	`Wm*Wn,Acc,Wx,Wxd,Wy,Wyd`[1]	Multiply Wm by Wn to Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
		`MPY`	`Wm*Wm,Acc,Wx,Wxd,Wy,Wyd`[1]	Square Wm to Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
50	`MPY.N`	`MPY.N`	`Wm*Wn,Acc,Wx,Wxd,Wy,Wyd`[1]	-(Multiply Wm by Wn) to Accumulator	1	1	None
51	`MSC`	`MSC`	`Wm*Wm,Acc,Wx,Wxd,Wy,Wyd,AWB`[1]	Multiply and Subtract from Accumulator	1	1	OA,OB,OAB, SA,SB,SAB

Note 1: These instructions are available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

2: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

TABLE 30-9: DC CHARACTERISTICS: WATCHDOG TIMER DELTA CURRENT (ΔIWDT)(1)

DC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended		
Parameter No.	**Typ.**	**Max.**	**Units**	**Conditions**	
DC61d	8	—	µA	-40°C	3.3V
DC61a	10	—	µA	+25°C	
DC61b	12	—	µA	+85°C	
DC61c	13	—	µA	+125°C	

Note 1: The ΔIWDT current is the additional current consumed when the module is enabled. This current should be added to the base IPD current. All parameters are characterized but not tested during manufacturing.

TABLE 30-10: DC CHARACTERISTICS: DOZE CURRENT (IDOZE)

DC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Parameter No.	**Typ.**	**Max.**	**Doze Ratio**	**Units**	**Conditions**		
Doze Current (IDOZE)(1)							
DC73a(2)	35	—	1:2	mA	-40°C	3.3V	FOSC = 140 MHz
DC73g	20	30	1:128	mA			
DC70a(2)	35	—	1:2	mA	+25°C	3.3V	FOSC = 140 MHz
DC70g	20	30	1:128	mA			
DC71a(2)	35	—	1:2	mA	+85°C	3.3V	FOSC = 140 MHz
DC71g	20	30	1:128	mA			
DC72a(2)	28	—	1:2	mA	+125°C	3.3V	FOSC = 120 MHz
DC72g	15	30	1:128	mA			

Note 1: IDOZE is primarily a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption. The test conditions for all IDOZE measurements are as follows:

- Oscillator is configured in EC mode and external clock is active, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{\text{MCLR}}$ = VDD, WDT and FSCM are disabled
- CPU, SRAM, program memory and data memory are operational
- No peripheral modules are operating; however, every peripheral is being clocked (all PMDx bits are zeroed)
- CPU is executing `while(1)` statement
- JTAG is disabled

2: Parameter is characterized but not tested in manufacturing.

TABLE 30-11: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
DI60a	I_{ICL}	**Input Low Injection Current**	0	—	-5(4,7)	mA	All pins except V_{DD}, V_{SS}, AV_{DD}, AV_{SS}, $\overline{MCLR}$, V_{CAP} and RB7
DI60b	I_{ICH}	**Input High Injection Current**	0	—	+5(5,6,7)	mA	All pins except V_{DD}, V_{SS}, AV_{DD}, AV_{SS}, $\overline{MCLR}$, V_{CAP}, RB7 and all 5V tolerant pins(6)
DI60c	$\sum I_{ICT}$	**Total Input Injection Current (sum of all I/O and control pins)**	-20(8)	—	+20(8)	mA	Absolute instantaneous sum of all ± input injection currents from all I/O pins (| I_{ICL} + | I_{ICH} |) ≤ $\sum I_{ICT}$

Note 1: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current can be measured at different input voltages.

2: Negative current is defined as current sourced by the pin.

3: See the **"Pin Diagrams"** section for the 5V tolerant I/O pins.

4: V_{IL} source < (V_{SS} – 0.3). Characterized but not tested.

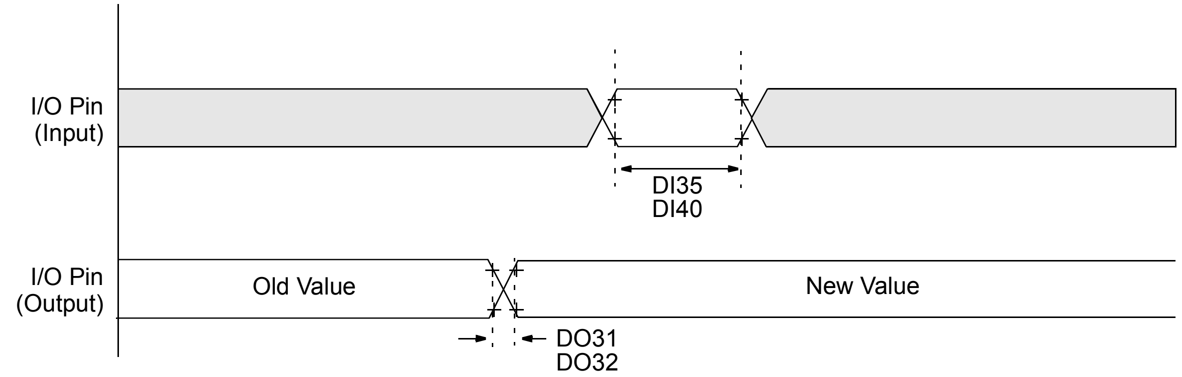
5: Non-5V tolerant pins V_{IH} source > (V_{DD} + 0.3), 5V tolerant pins V_{IH} source > 5.5V. Characterized but not tested.

6: Digital 5V tolerant pins cannot tolerate any "positive" input injection current from input sources > 5.5V.

7: Non-zero injection currents can affect the ADC results by approximately 4-6 counts.

8: Any number and/or combination of I/O pins not excluded under I_{ICL} or I_{ICH} conditions are permitted provided the mathematical "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

FIGURE 30-3: I/O TIMING CHARACTERISTICS



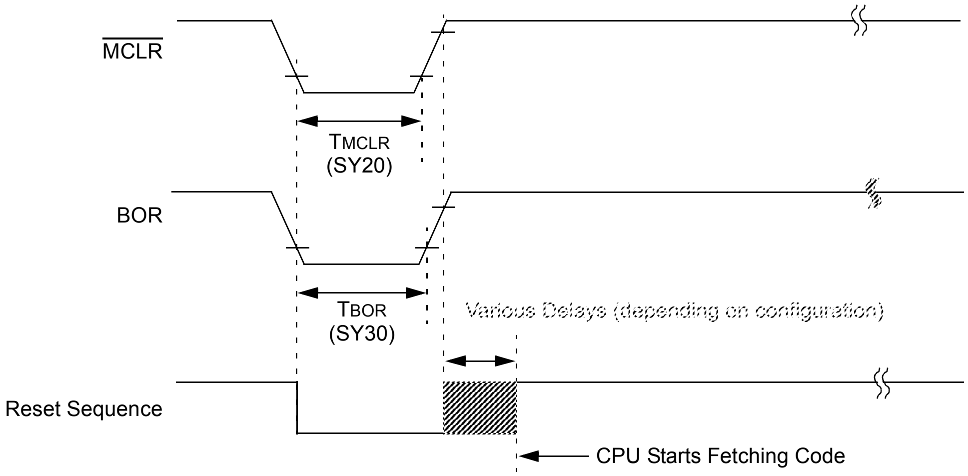
Note: Refer to Figure 30-1 for load conditions.

TABLE 30-21: I/O TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.[1]**	**Max.**	**Units**	**Conditions**
DO31	TIOR	Port Output Rise Time	—	5	10	ns	
DO32	TIOF	Port Output Fall Time	—	5	10	ns	
DI35	TINP	INTx Pin High or Low Time (input)	20	—	—	ns	
DI40	TRBP	CNx High or Low Time (input)	2	—	—	TCY	

Note 1: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

FIGURE 30-4: BOR AND MASTER CLEAR RESET TIMING CHARACTERISTICS



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